

Semiconductor devices —

Part 14-3: Semiconductor sensors — Pressure sensors

ICS 31.080.99

National foreword

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The UK participation in its preparation was entrusted to Technical Committee EPL/47, Semiconductors, which has the responsibility to:

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Part 14-3: Semiconductor sensors – Pressure sensors

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*Partie 14-3:
Capteurs à semiconducteurs –
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INTERNATIONAL ELECTROTECHNICAL COMMISSION

SEMICONDUCTOR DEVICES –

Part 14-3: Semiconductor sensors –
Pressure sensors

FOREWORD

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The text of this standard is based on the following documents:

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47E/191/FDIS	47E/195/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 3.

A bilingual version of this standard may be issued at a later date.

The committee has decided that the contents of this publication will remain unchanged until 2006. At this date, the publication will be

- reconfirmed;
- withdrawn;
- replaced by a revised edition, or
- amended.

INTRODUCTION

This part of IEC 60747 should be read in conjunction with IEC 60747-1. It provides basic information on semiconductor

- terminology;
- letter symbols;
- essential ratings and characteristics;
- measuring methods;
- acceptance and reliability.